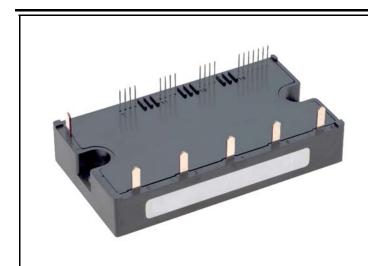


<Intelligent Power Modules>

PM75RG1AP065

FLAT-BASE TYPE INSULATED PACKAGE



FEATURE

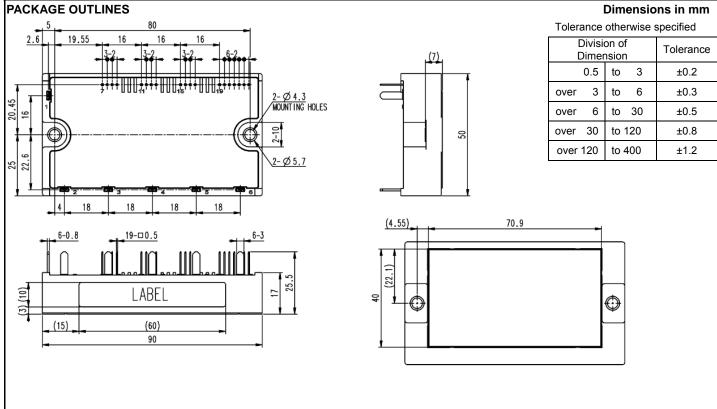
- a) Adopting Full-Gate CSTBT™ chip.
- b) The over-temperature protection which detects the chip surface temperature of CSTBTTM is adopted.
- c) Error output signal is available from each protection upper and lower arm of IPM.
- d) Outputting an error signal corresponding to the abnormal state (error mode identification)

UL Recognized under UL1557, File No. E323585

This product is compliant with the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive 2011/65/EU.

APPLICATION

General purpose inverter, servo drives and other motor controls



TERMINAL CODE

1.B, 2.P, 3.N, 4.U, 5.V, 6.W, 7.Vupc, 8.Ufo, 9.Up, 10.Vup1, 11.Vvpc, 12.Vfo, 13.Vp, 14.Vvp1, 15.Vwpc, 16.Wfo, 17.Wp, 18.Vwp1, 19.Vnc, 20.Vn1, 21.BR, 22.Un, 23.Vn, 24.Wn, 25.Fo

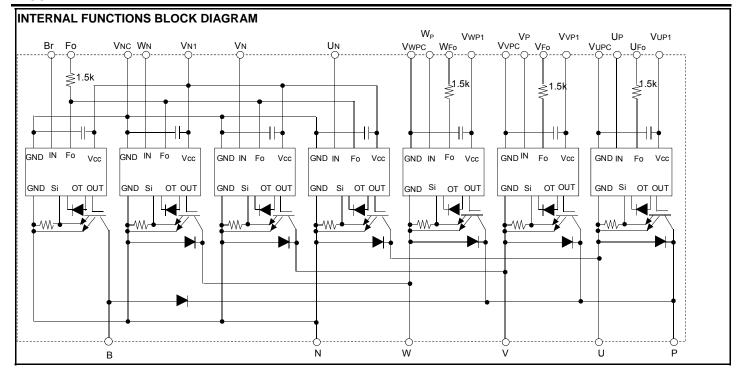
Publication date: Nov, 2017

1

PM75RG1AP065

HIGH POWER SWITCHING USE

INSULATED TYPE



MAXIMUM RATINGS (Tvj = 25°C, unless otherwise noted)

INVERTER PART

Symbol	Parameter	Conditions	Ratings	Unit
V _{CES}	Collector-Emitter Voltage	V _D =15 V, V _{CIN} =15 V	650	V
Ic	Collector Current	T _C =25 °C	75	^
I _{CRM}	Collector Current	Pulse	150	Α
P _{tot}	Total Power Dissipation	T _C =25 °C	297	W
l _E	Emitter Current	T _C =25 °C	75	_
I _{ERM}	(Free-wheeling Diode Forward current)	Pulse	150	Α
Tvj	Junction Temperature		-20 ~ +150	°C

^{*:} Tc measurement point is just under the chip.

BRAKE PART

Symbol	Parameter	Conditions	Ratings	Unit
V_{CES}	Collector-Emitter Voltage	V _D =15 V, V _{CIN} =15 V	650	V
Ic	Collector Current	T _C =25 °C	50	^
I _{CRM}	Collector Current	Pulse	100	A
P _{tot}	Total Power Dissipation	T _C =25 °C	240	W
V _{R(DC)}	Diode Rated Reverse DC Voltage	T _C =25 °C	650	V
l _F	Diode Forward Current	T _C =25 °C	50	Α
Tj	Junction Temperature		-20 ~ +150	°C

^{*:} Tc measurement point is just under the chip.

CONTROL PART

Symbol	Parameter	Conditions	Ratings	Unit
V_D	Supply Voltage	Applied between: V_{UP1} - V_{UPC} , V_{VP1} - V_{VPC} , V_{WP1} - V_{WPC} , V_{N1} - V_{NC}	20	V
V_{CIN}	Input Voltage	Applied between: U_P - V_{UPC} , V_P - V_{VPC} , W_P - V_{WPC} , U_N , V_N , W_N , Br - V_{NC}	20	V
V_{FO}	Fault Output Supply Voltage	Applied between: U _{FO} -V _{UPC} , V _{FO} -V _{VPC} , W _{FO} -V _{WPC} , Fo-V _{NC}	20	V
I _{FO}	Fault Output Current	Sink current at U _{FO} , V _{FO} , W _{FO} , Fo terminals	20	mA

PM75RG1AP065

HIGH POWER SWITCHING USE INSULATED TYPE

TOTAL SYSTEM

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC(PROT)}	Supply Voltage Protected by SC	V _D =13.5 V~16.5 V, Inverter Part, Tvj=+125°C start	400	V
T_{stg}	Storage Temperature	-	-40 ~ +125	°C
Tc	Operating Case Temperature	-	-20 ~ +125	°C
V _{isol}	Isolation Voltage	60Hz, Sinusoidal, Charged part to Base plate, AC 1min, RMS	2500	V

^{*:} Tc measurement point is just under the chip.

THERMAL RESISTANCE

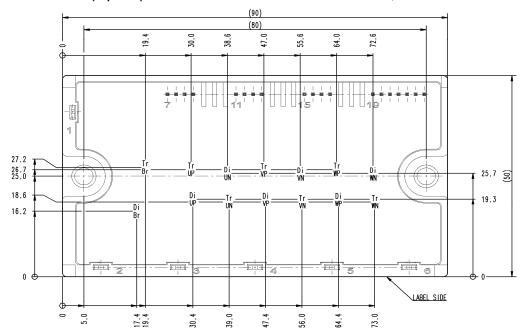
Symbol	Parameter	Conditions	Limits			Linit
		Conditions	Min.	Тур.	Max.	Unit
R _{th(j-c)Q}		Inverter, Junction to case, IGBT, per 1 element (Note1)	-	-	0.42	
R _{th(j-c)D}	Thermal Resistance	Inverter, Junction to case, FWD, per 1 element (Note1)	-	-	0.68	K/W
$R_{th(j-c)Q}$		Brake, Junction to case, IGBT, per 1 element (Note1)	-	-	0.52	I IVVV
R _{th(j-c)D}		Brake, Junction to case, FWD, per 1 element (Note1)	-	-	0.88	
R _{th(c-s)}	Contact Thermal Resistance	Case to heat sink, per 1 module,	- 19.1		_	K/kW
		Thermal grease applied (Note.1, 2)	-	13.1	-	TORVV

Note1. If you use this value, $R_{\text{th(s-a)}}\,\text{should}$ be measured just under the chips.

Note2. Typical value is measured by using thermally conductive grease of λ =0.9W/(m·K), $D_{\text{(C-S)}}$ =50 μ m.

CHIP LOCATION (Top view)

Dimension in mm, torelance: ±1mm



Tr** : IGBT Di** : FWD

<Intelligent Power Modules>

PM75RG1AP065

HIGH POWER SWITCHING USE

INSULATED TYPE

ELECTRICAL CHARACTERISTICS (Tvj= 25°C, unless otherwise noted)

INVERTER PART

Cumbal	Parameter	Conditions			Limits			Unit
Symbol	Farameter	Gonditons		Min.	Тур.	Max.	Offic	
		V _D =15 V, I _C =75 A Tvj=25 °C	T:-25 °C	Terminal	-	-	1.75	
V	Collector-Emitter Saturation Voltage		1 Vj=25 C	Chip	-	1.25	-	V
V _{CEsat}		V _{CIN} =0 V, Pulsed, (Fig.1)	Tvj=125 °C	Terminal	-	-	2.0	V
		V _{CIN} =0 V, Pulsed, (Fig. I)	1 Vj=125 C	Chip	1	1.33	-	
V	Emitter-Collector Voltage	V _D =15 V, I _E =75 A,	Tvj=25 °C	Terminal	-	-	1.95	
		V _D -13 V, 1 _E -73 A,	1 Vj-25 C	Chip	-	1.40	-	V
V_{EC}		V _{CIN} = 15 V, pulsed, (Fig.2) Tvj=125 °C	Tvi=125 °C	Terminal	ı	-	2.05	V
			Chip	ı	1.45	1		
t_{on}		V _D =15 V, V _{CIN} =0 V↔15 V,			0.3	0.6	1.2	
t _{rr}		V _{CC} =300 V, I _C =75A,			-	0.2	0.65	
$t_{c(on)}$	Switching Time	Tvj=125 °C,			-	0.17	0.75	μs
t _{off}		Inductive Load			-	1.0	2.3	
$t_{c(off)}$		(Fig.3, 4)			1	0.13	0.4	
1	Collector-Emitter Cut-off Current	V _{CE} =V _{CES} , V _D =15 V, V _{CIN} =15 V (Fig.5)		Tvj=25 °C	1	-	1	mA
I _{CES}				V _{CIN} =15 V (Fig.5) Tvj=125 °C	Tvj=125 °C	-	-	10

BRAKE PART

Cumhal	Doromotor	Conditions			Limits			Unit
Symbol	Parameter	Condition	Conditions			Тур.	Max.	Unit
		V _D =15 V, I _C =50 A Tvj=25 °C	Tvj=25 °C	Terminal	-	-	1.7	
.,		V _D =13 V, 1 _C =30 A	1 1 2 5 6	Chip	-	1.25	-	.,
V _{CEsat}	Collector-Emitter Saturation Voltage	V _{CIN} =0 V, Pulsed, (Fig.1)	Tvj=125 °C	Terminal	-	-	1.95	V
		V _{CIN} -0 V, Fulsed, (Fig. 1)	1 Vj=125 C	Chip	-	1.33	-	
		Tvj=25	Tv:-25 °C	Terminal	-	-	1.9	
\	Diode Forward Voltage		1 Vj-25 C	Chip	-	1.40	-	\ ,
V_{FM}	Diode Forward Voltage	I _F =50A	T : 405 00	Terminal	-	-	2.0	V
		Tvj=125 °C		Chip	-	1.45	-	
	0-11	V _{CE} =V _{CES} , V _D =15 V, V _{CIN} =15 V (Fig.5)		Tvj=25 °C	-	-	1	4
I _{CES}	Collector-Emitter Cut-off Current			Tvj=125 °C	-	-	10	mA

<Intelligent Power Modules>

PM75RG1AP065

HIGH POWER SWITCHING USE

INSULATED TYPE

ELECTRICAL CHARACTERISTICS (Tvj = 25°C, unless otherwise noted)

CONTROL PART

Cumbal	Dorometer	Conditions	Conditions		Limits		
Symbol	Parameter	Conditions			Тур.	Max.	Unit
		V =45 V V =45 V	V _{P1} -V _{PC}	-	4	6	
	Oireanit Ourreact	V _D =15 V, V _{CIN} =15 V	V _{N1} -V _{NC}	-	16	24	
I _D	Circuit Current	V _D =15 V, V _{CIN} =0 V←15 V, V _{CC} =400 V	V _{P1} -V _{PC}	-	12	15	mA
		I _C =0A, Tvj=125 °C, f _C ≤20kHz	V _{N1} -V _{NC}	-	46	54	
$V_{th(ON)}$	Input ON Threshold Voltage	Applied between:		1.2	1.5	1.8	.,
$V_{th(OFF)}$	Input OFF Threshold Voltage	U_{P} - V_{UPC} , V_{P} - V_{VPC} , W_{P} - V_{WPC} , U_{N} , V_{N} , W_{N} ,	Br-V _{NC}	1.7	2.0	2.3	V
00	Short Circuit Trip Level	00 T : 405 00 W 45 W (F: 0.0)	Inverter Brake	150	-	-	A
SC		-20≤Tvj≤125 °C, V _D =15 V (Fig.3, 6)		100	-	-	
t _{d(SC)}	Short Circuit Current Delay Time	V _D =15 V, Tvj=125 °C (Fig.3, 6)		-	2.0	-	μs
ОТ	0 7 1 0 1 11	Detect town continue of ICDT chin confere	Trip level	150	-	-	۰.
OT _(hys)	Over Temperature Protection	Detect temperature of IGBT chip surface	Hysteresis	-	20	-	°C
UV _t	Supply Circuit		Trip level	11.0	12.0	12.7	V
UV _r	Under-Voltage Protection	-	Reset level	-	12.5	-	V
I _{FO(H)}	Fault Outrant Outrant	V 45 V V 45 V (N-4-0)		-	-	0.01	
I _{FO(L)}	Fault Output Current	V _D =15 V, V _{FO} =15 V (Note3)		-	10	15	- mA
			ОТ	-	8.0	-	
t _{FO}	Fault Output Pulse Width	V _D =15 V (Note3)	UV	-	4.0	-	ms
			SC	-	2.0	-	

Note3. Fault output is given only when the internal SC, OT & UV protections schemes of either upper or lower arm device operate to protect it.

MECHANICAL RATINGS AND CHARACTERISTICS

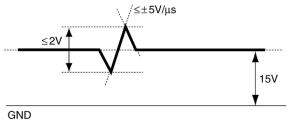
Symbol	Parameter	Conditions	Limits			Unit
		Conditions	Min.	Тур.	Max.	Offic
Ms	Mounting Torque	Mounting part screw : M4	1.5	1.7	2.0	N•m
m	mass	-	-	175	-	g

RECOMMENDED CONDITIONS FOR USE

Symbol	Parameter	Conditions	Recommended value	Unit
V _{CC}	Supply Voltage	Applied across P-N terminals	≤ 400	V
V _D	Control Supply Voltage Applied between: Vup1-Vupc, Vvp1-Vvpc, Vwp1-Vwpc, Vn1-Vnc (Note4)		15.0±1.5	٧
V _{CIN(ON)}	Input ON Voltage	Applied between :	≤ 0.8	V
V _{CIN(OFF)}	Input OFF Voltage	U_P - V_{UPC} , V_P - V_{VPC} , W_P - V_{WPC} , U_N , V_N , W_N , Br - V_{NC}	≥ 9.0	V
f _{PWM}	PWM Input Frequency	Using Application Circuit of Fig. 8	≤ 20	kHz
t _{dead}	Arm Shoot-through Blocking Time	For IPM's each input signals (Fig.7)	≥ 2.0	μs

This product is compliant with the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive 2011/65/EU.

Note4. With ripple satisfying the following conditions: dv/dt swing ≤ ±5 V/µs, Variation ≤ 2 V peak to peak



PRECAUTIONS FOR TESTING

- 1. Before applying any control supply voltage (V_D), the input terminals should be pulled up by resistors, etc. to their corresponding supply voltage and each input signal should be kept off state.
 - After this, the specified ON and OFF level setting for each input signal should be done.
- 2. When performing "SC" tests, the turn-off surge voltage spike at the corresponding protection operation should not be allowed to rise above VCES rating of the device.

(These test should not be done by using a curve tracer or its equivalent.)

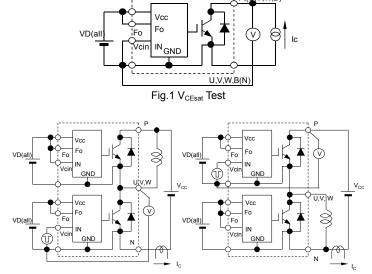
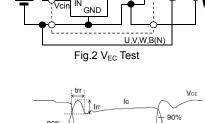


Fig.3 Switching time and SC test circuit



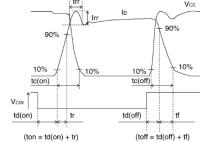


Fig.4 Switching time test waveform

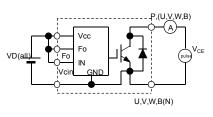


Fig.5 I_{CES} Test

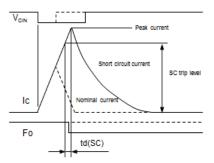
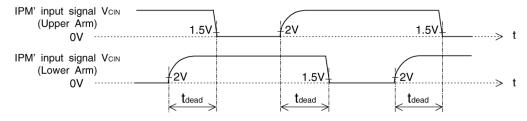


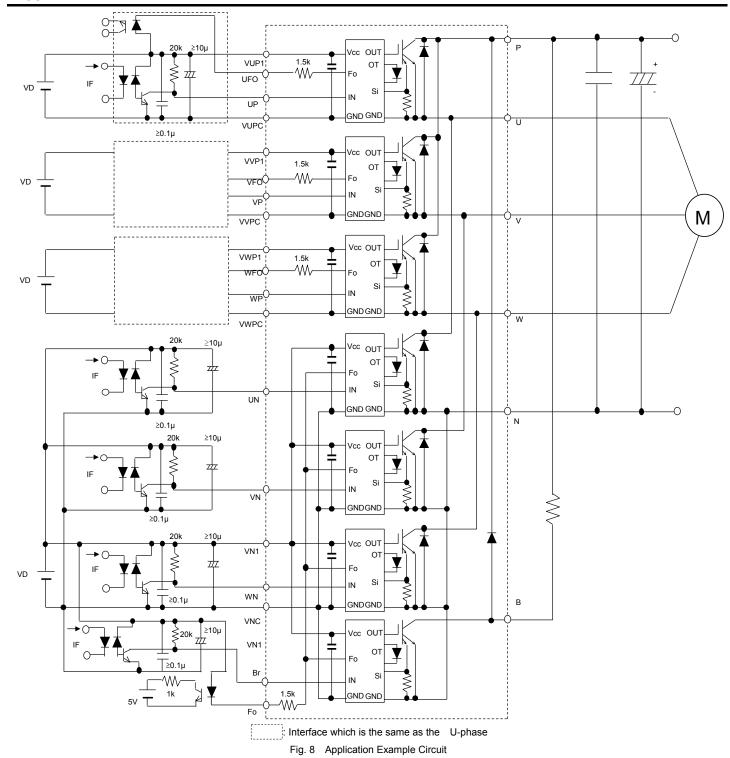
Fig.6 SC test waveform



1.5V: Input on threshold voltage Vth(on) typical value, 2V: Input off threshold voltage Vth(off) typical value

Fig. 7 Dead time measurement point example

INSULATED TYPE

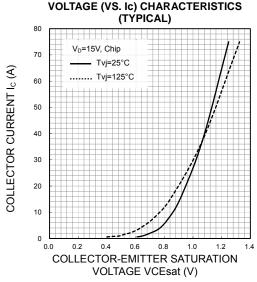


NOTES FOR STABLE AND SAFE OPERATION;

- Design the PCB pattern to minimize wiring length between opto-coupler and IPM's input terminal, and also to minimize the stray capacity between the input and output wirings of opto-coupler.
- · Connect low impedance capacitor between the Vcc and GND terminal of each fast switching opto-coupler.
- Fast switching opto-couplers: t_{PLH} , $t_{PHL} \le 0.8 \mu s$, Use High CMR type.
- Slow switching opto-coupler: CTR > 100% (*can be applied to Brake part input signal, in this case, resistor should be selected properly).
- Use 4 isolated control power supplies (V_D). Also, care should be taken to minimize the instantaneous voltage charge of the power supply.
- Make inductance of DC bus line as small as possible, and minimize surge voltage using snubber capacitor between P and N terminal.

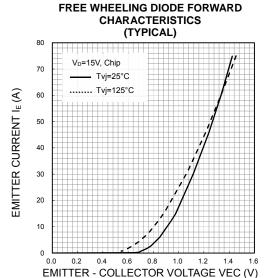
INSULATED TYPE

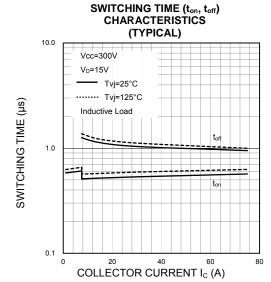
PERFORMANCE CURVES Inverter part

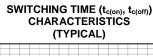


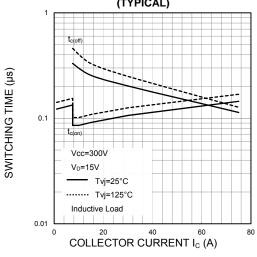
COLLECTOR-EMITTER SATURATION

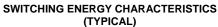


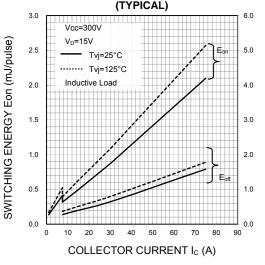




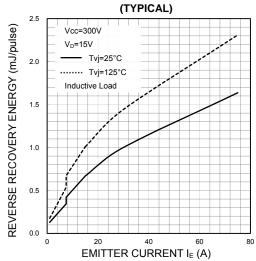




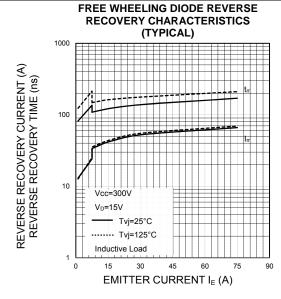


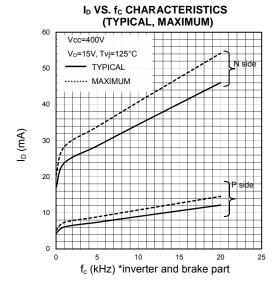


FREE WHEELING DIODE REVERSE RECOVERY
ENERGY CHARACTERISTICS
(TYPICAL)

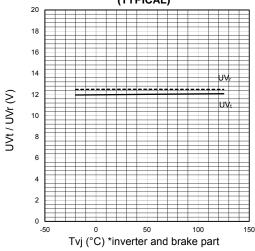


SWITCHING ENERGY Eoff (mJ/pulse)

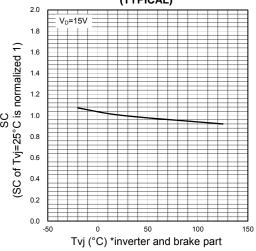




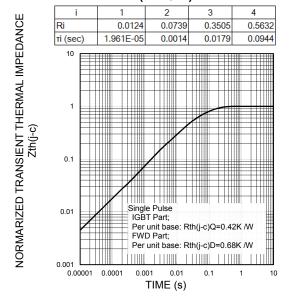
UV TRIP LEVEL VS. Tvj CHARACTERISTICS (TYPICAL)



SC TRIP LEVEL VS. TVJ CHARACTERISTICS (TYPICAL)



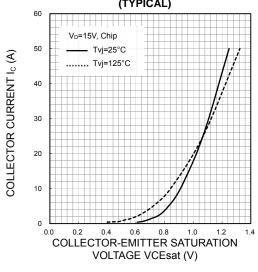
TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (TYPICAL)



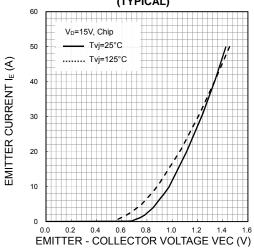
HIGH POWER SWITCHING USE INSULATED TYPE

PERFORMANCE CURVES Brake part

COLLECTOR-EMITTER SATURATION VOLTAGE (VS. Ic) CHARACTERISTICS (TYPICAL)



FREE WHEELING DIODE FORWARD CHARACTERISTICS (TYPICAL)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (TYPICAL)

ш	I	1	2	3	4
Ō	Ri	0.0124	0.0739	0.3505	0.5632
NORMARIZED TRANSIENT THERMAL IMPEDANCE Zth(j-c)	ті (sec)	1.961E-05	0.0014	0.0179	0.0944
	10				
₽					
≤					
₫					
≥	1				
甲	. 🗐				
ن ټ			/		
卢늗					
回討					
Ş	0.1				
₹					
Ľ			++++++++++++++++++++++++++++++++++++		
Ω		Sinal	le Pulse	TIIIII. TIII	III. TITIII
ZI ZE	0.01		T Part;		
Ä		Per	unit base: R	th(j-c)Q=0.5	2K /W
Ž			D Part; unit base: R	th(i_c)D=0.8	8K W
S.			I I I I I I I I I	.u.ig-c)D-0.0	
ž	0.001				
	0.00001	0.0001 0.0		0.1	1 10
			TIME (s)		

PM75RG1AP065

HIGH POWER SWITCHING USE INSULATED TYPE

Keep safety first in your circuit designs!

This product is designed for industrial application purpose. The performance, the quality and support level of the product is guaranteed by "Customer's Std. Spec.".

Mitsubishi Electric Corporation puts its reasonable effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them by the reliability lifetime such as Power Cycle, Thermal Cycle or others, or to be used under special circumstances(e.g. high humidity, dusty, salty, highlands, environment with lots of organic matter / corrosive gas / explosive gas, or situation which terminal of semiconductor products is received strong mechanical stress). In the customer's research and development, please evaluate it not only with a single semiconductor product but also in the entire system, and judge whether it's applicable. Furthermore, trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits (e.g. appropriate fuse or circuit breaker between a power supply and semiconductor products), (ii) use of non-flammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

- •These materials are intended as a reference to assist our customers in the selection of the Mitsubishi semiconductor product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Mitsubishi Electric Corporation or a third party.
- •Mitsubishi Electric Corporation assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, or circuit application examples contained in these materials.
- •All information contained in these materials, including product data, diagrams and charts represents information on products at the time of publication of these materials, and are subject to change by Mitsubishi Electric Corporation without notice due to product improvements or other reasons. It is therefore recommended that customers contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor for the latest product information before purchasing a product listed herein.

The information described here may contain technical inaccuracies or typographical errors. Mitsubishi Electric Corporation assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors.

Please also pay attention to information published by Mitsubishi Electric Corporation by various means, including the Mitsubishi Semiconductor home page (www.MitsubishiElectric.com/semiconductors/).

- •When using any or all of the information contained in these materials, including product data, diagrams, and charts, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Mitsubishi Electric Corporation assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
- •Mitsubishi Electric Corporation semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Therefore, this product should not be used in such applications. Please contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
- •In the case of new requirement is available, this material will be revised upon consultation.
- •The prior written approval of Mitsubishi Electric Corporation is necessary to reprint or reproduce in whole or in part these materials.
- •If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.
- Any diversion or re-export contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
- •Please contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor for further details on these materials or the products contained therein.

Generally the listed company name and the brand name are the trademarks or registered trademarks of the respective companies.

Note:

The characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

© 2018 MITSUBISHI ELECTRIC CORPORATION. ALL RIGHTS RESERVED.